



Specification

Client Name : _____
:

Client P/N : _____
:

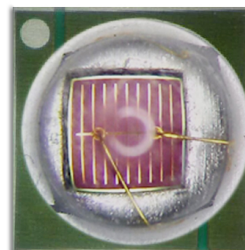
ProductP/N : CL-SFD3535IR-740-B-02
:

Sending Date: _____
:

Approval	Audit	Approval	Audit	Confirmation
☐ Qualified ☐ Disqualified		DATE:		



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

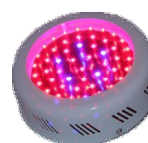


Features

- Dimension : 3.45mm×3.45mm×1.9mm
- Long operating life
- High efficiency
- Lambertian radiation pattern
- Low voltage DC operated
- Cool beam, safe to the touch
- High heat dissipation efficiency
- Superior ESD protection

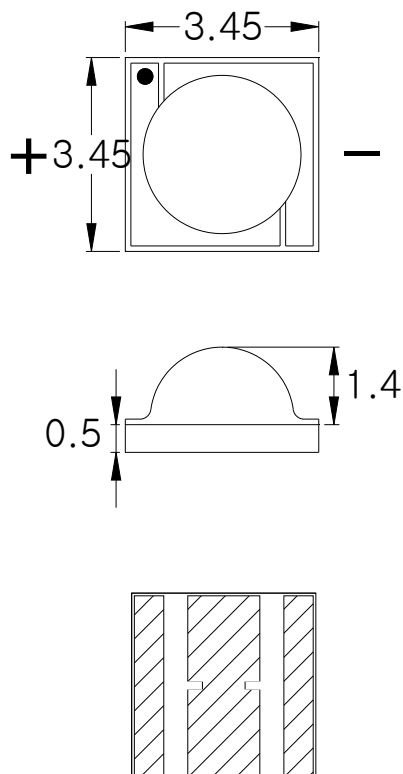
Applications

Small size, Flexible design

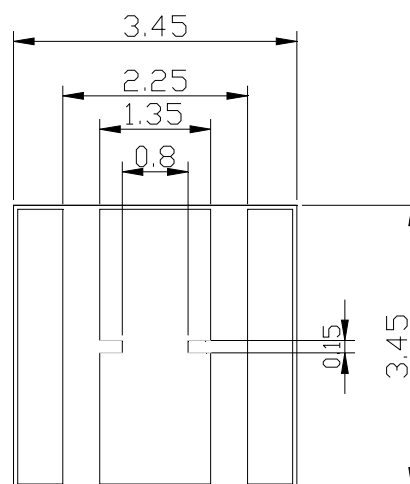


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Package Dimensions



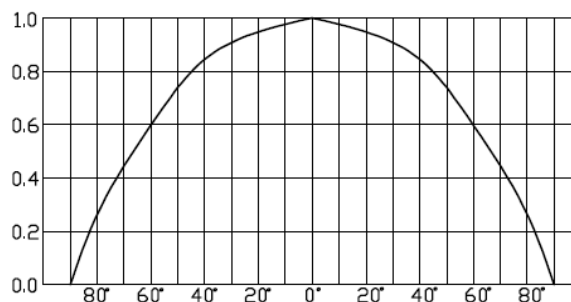
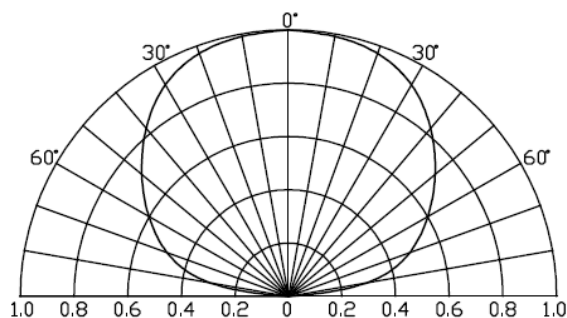
Recommended Soldering



Notes :

1. All dimension units are millimeters.
2. All dimension tolerance is $\pm 0.2\text{mm}$ unless otherwise noted.

Radiation Pattern



Typical Optical/ Electrical Characteristics @T_a=25°C

T_a=25°C

Symbol	Item	Min.	Typ.	Max.	Units	Test Conditions
ΦV	Luminous Flux	0.2	0.4	—	lm	IF=700mA
Φe	Radiation Power	—	450	—	mW	IF=700mA
VF	Forward Voltage [1]	1.8	—	2.4	V	IF=700mA
λ _p	peak wavelength	735		745	nm	IF=700mA
2θ _{1/2}	50% power angle	—	130	—	deg	IF=700mA
IR	Reverse Current	—	—	30	uA	VR = 5V

Notes :

1.Tolerance of measurement of forward voltage±0.1V 、 peak Wavelength±2.0nm 、 luminous flux±5%

Absolute Maximum Ratings

TA=25°C

Item	Symbol	Absolute Maximum Rating	Units
Power dissipation[1]	Pd	3	W
DC Forward Current[1]	I _F	700	mA
Peak Forward Current	I _{FP}	800	mA
Reverse Voltage[1]	V _R	5	V
Operating Temperature	Topr	-20°C To +65°C	
Storage Temperature	Tstg	0°C To +40°C	

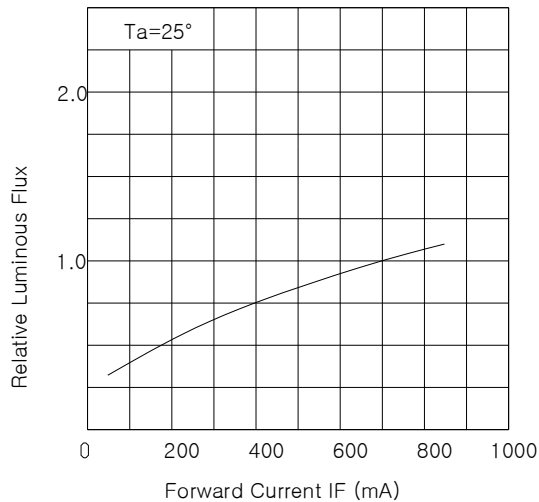
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

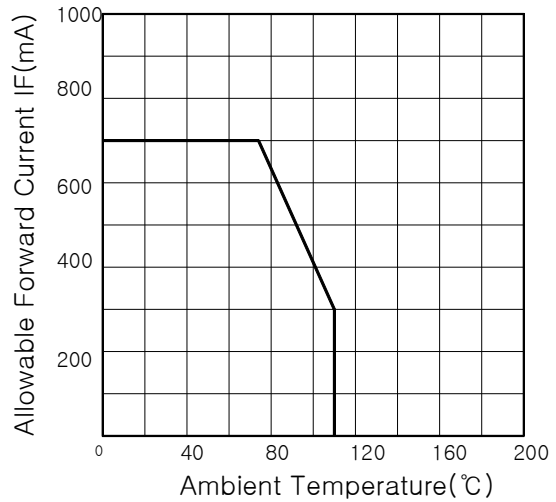
2. The temperature of Aluminum PCB do not exceed 55°C.

Typical Optical/Electrical Characteristics Curves ($T_a=25^{\circ}\text{C}$ Unless Otherwise Noted)

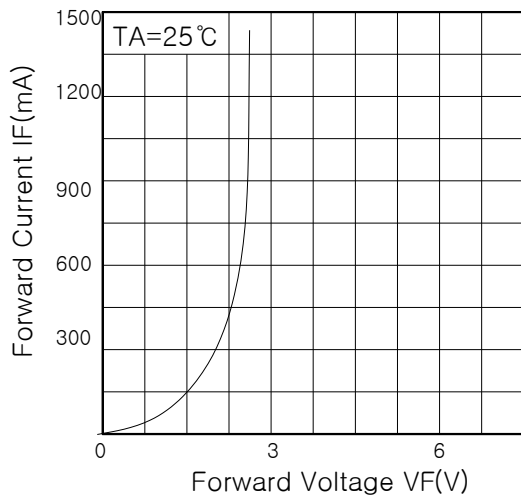
Relative Luminous Flux – IF



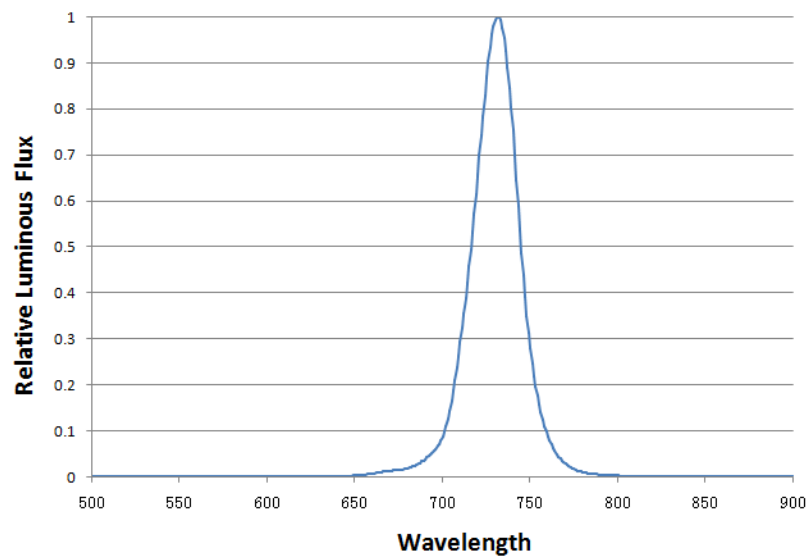
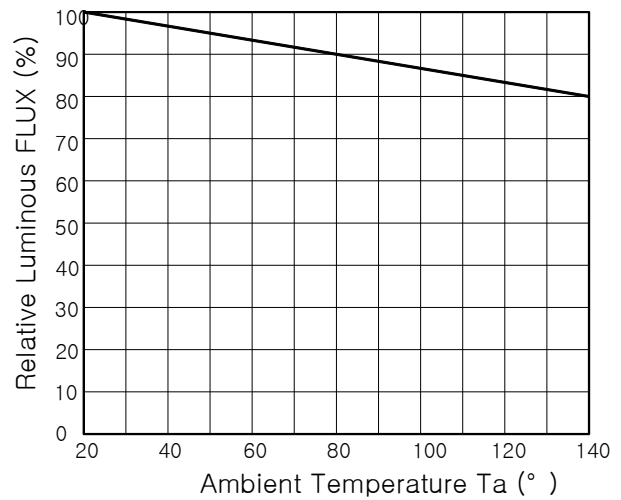
Allowable Forward Current – T_a



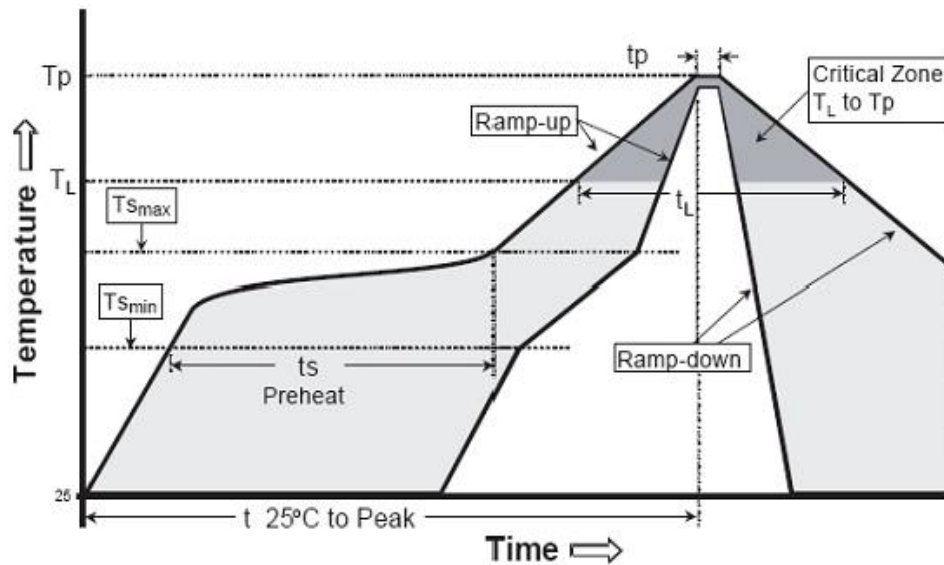
IF – VF



Relative Luminous Flux – T_a



Soldering :



Reflow soldering

Caution :

1. wave peak and soak-stannum soldering etc. is not suitable for this products.
2. reflow soldering should not be done more than one time
3. The peak reflow temperature is $260 \pm 10^{\circ}\text{C}$, not more than 40 seconds
4. Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, suitable tools have to be used.
5. when soldering, do not put stress on the LEDs during heating.
6. After soldering, do not warp the LED. do not stack PCBs or assemblies containing K Series LEDs so that anything rests on the LED lens.

Test

1. Drive IFP Conditions : Pulse Width $\leq 10\text{msec}$ duty $\leq 1/10$.
2. All high power emitter LED products mounted on aluminum metal-core printed circuit board, can be lighted directly, but we do not recommend lighting the high power products for more than 5 seconds without a appropriate heat dissipation equipment.

Label

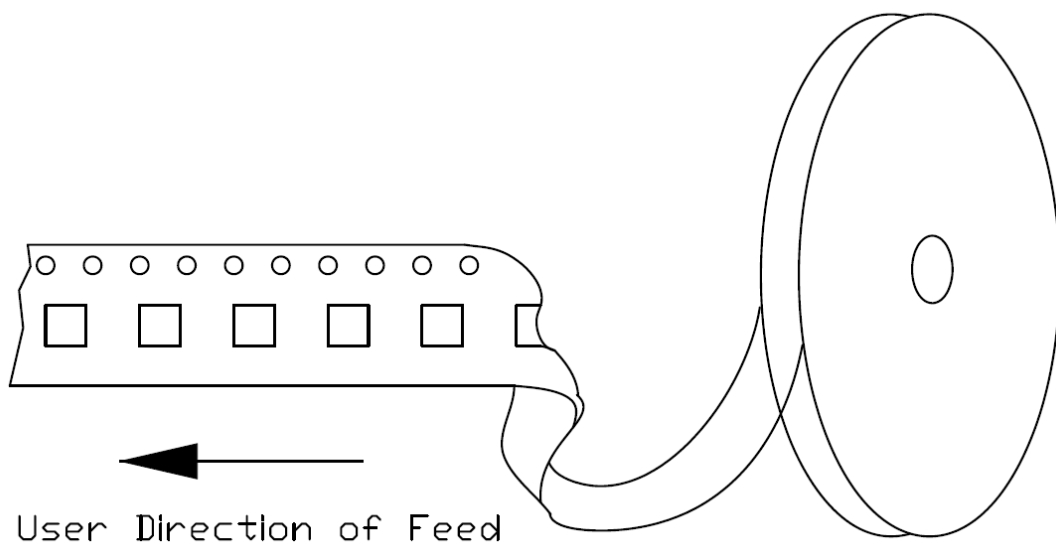
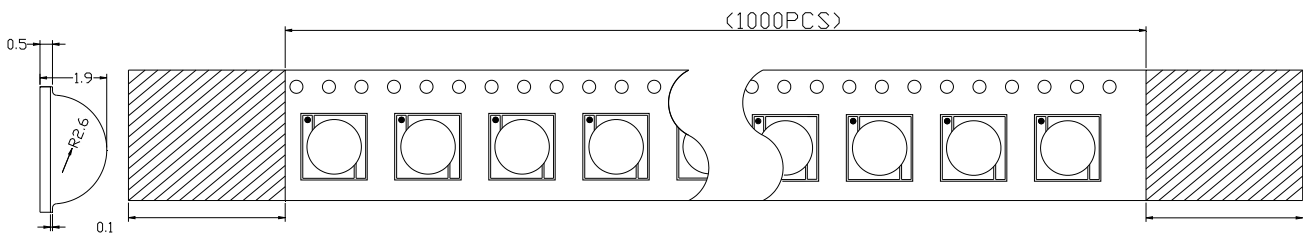
ΦV : Luminous Flux rank

VF: Forward voltage rank

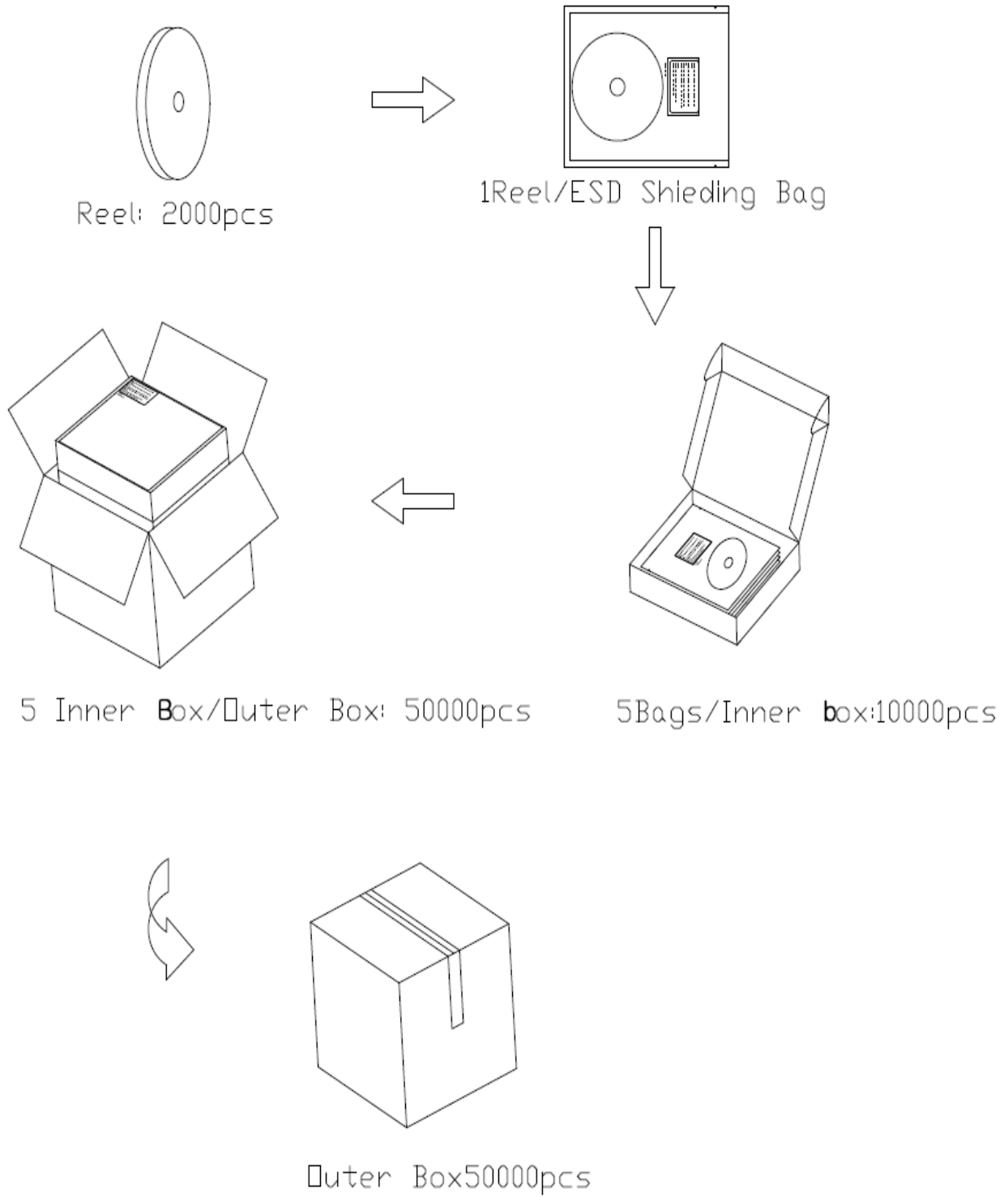
WP: Peak Wave Length

LOT.NO: Lot Number

Tape Specifications(Units:mm)



Packing



Precaution for use

1.Storage

To avoid the moisture penetration ,we recommend storing LEDs in a dry box (or a desiccator) with a desiccant. The recommended conditions are temperature 5 to 30 degrees Centigrade. Humidity 60% maximum.

2.Precaution after opening packing

2.1.Soldering should be done right after opening the package (within 24Hrs).

2.2.Keeping of a fraction

-Sealing

-Temperature: 5~30 ; Humidity: less than 30 °

2.3.If the package has been opened than 1 week or the color of desiccant changed, components should be dried for 10-12 Hrs at $60\pm5^{\circ}\text{C}$.

3.Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.

4.Please avoid rapid cooling after soldering.

5.Components should not be mounted on warped direction of PCB.

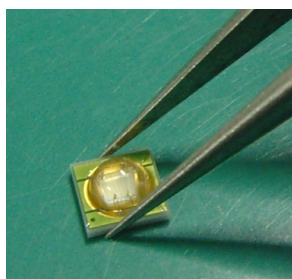
6.This device should not be used in any fluid such as water, oil ,organic solvent etc. When washing is required, Isopropyl Alcohol should be used.

7.Avoid touching Lens parts especially by sharp tools such as pincette.

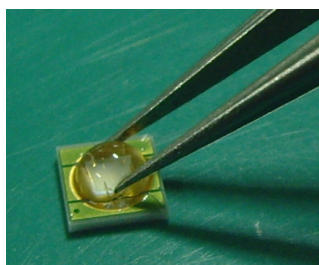
8.Please do not force over 1000g impact or pressure diagonally on the silicone lens. It will cause fatal damage on this product.

9.Please do not cover the silicone resin of the LEDs with other resin.

10.Do not use metal suction nozzle, rubber or silica gel suction nozzle is recommended.



OK



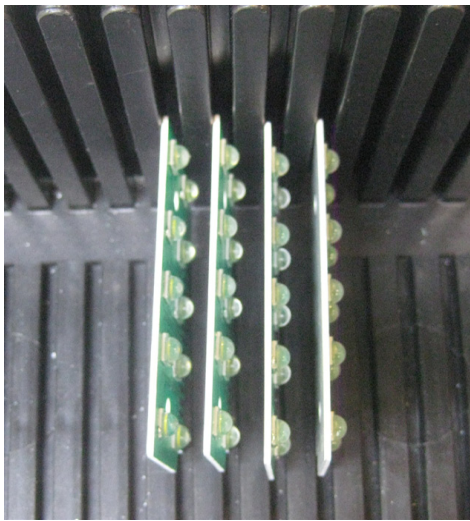
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Note:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous flux is 1/2 the optical centerline value.

2.The value only for reference.

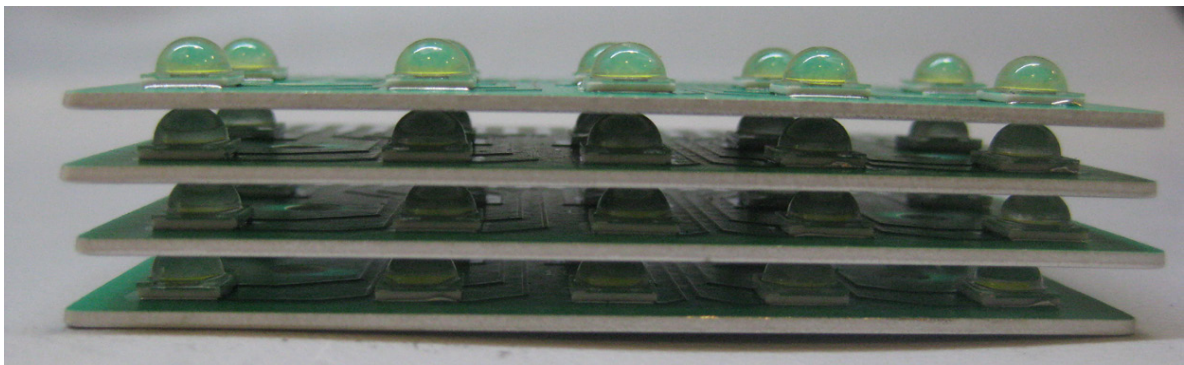
13. Do not stack PCBs or assemblies containing the LEDs so that anything rests on the LED lens. Force applied to the LED lens may result in the lens being knocked off. PCBs or assemblies containing the LEDs should be stacked in a way to allow at least 2 cm clearance above the LED lens.



OK



OK



NG